

L Number	Hits	Search Text	DB	Time stamp
3	14	(US-6333564-\$ or US-6080932-\$ or US-6114192-\$ or US-6038136-\$ or US-5976912-\$ or US-5557150-\$ or US-5653020-\$).did.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/26 15:58
5	2	((("6518654") or ("6329220")).PN.	USPAT	2004/06/26 15:59
4	7	(US-6333564-\$ or US-6080932-\$ or US-6114192-\$ or US-6038136-\$ or US-5976912-\$ or US-5557150-\$ or US-5653020-\$).did.	USPAT	2004/06/26 16:06
6	14	US-5930603-\$.DID. OR US-5914531-\$.DID. OR US-5293072-\$.DID. OR US-5650593-\$.DID. OR US-6049038-\$.DID. OR US-6225144-\$.DID. OR US-5448114-\$.DID. OR US-5583378-\$.DID. OR US-5708304-\$.DID. OR US-5625222-\$.DID. OR US-6261870-\$.DID. OR US-5604376-\$.DID. OR US-4641176-\$.DID. OR US-6002178-\$.DID.	USPAT	2004/06/26 16:09
7	4	("2570221").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/26 16:09
8	3	(US-5914531-\$ or US-6114192-\$).did. or (FR-2570221-\$).did.	USPAT; EPO	2004/06/26 16:17
9	1013170	mold\$4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/26 16:17
11	51370	mold\$4 and ((encapsulat\$4 or seal\$4) with (semiconductor or device or die or chip))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/26 16:42
12	15351	(mold\$4 and ((encapsulat\$4 or seal\$4) with (semiconductor or device or die or chip))) and (plural\$6 with (die or semiconducotr or chip or device))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/26 16:42
13	1719	((mold\$4 and ((encapsulat\$4 or seal\$4) with (semiconductor or device or die or chip))) and (plural\$6 with (die or semiconducotr or chip or device))) and rib	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/26 16:42
14	114	((mold\$4 and ((encapsulat\$4 or seal\$4) with (semiconductor or device or die or chip))) and (plural\$6 with (die or semiconducotr or chip or device))) and rib) and (mold with rib)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/26 16:41
15	91059	425/\$.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/26 16:41
16	36515	425/\$.ccls. and mold\$4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/26 16:41
17	8145	(425/\$.ccls. and mold\$4) and (die or semiconducotr or chip)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/26 16:41

18	1099	((425/\$.ccls. and mold\$4) and (die or semiconducotr or chip)) and ((encapsulat\$4 or seal\$4) with (semiconductor or device or die or chip))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/26 16:42
19	452	((425/\$.ccls. and mold\$4) and (die or semiconducotr or chip)) and ((encapsulat\$4 or seal\$4) with (semiconductor or device or die or chip))) and (plural\$6 with (die or semiconducotr or chip or device))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/26 16:42
20	49	((425/\$.ccls. and mold\$4) and (die or semiconducotr or chip)) and ((encapsulat\$4 or seal\$4) with (semiconductor or device or die or chip))) and (plural\$6 with (die or semiconducotr or chip or device))) and rib	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/26 16:42
21	37	((425/\$.ccls. and mold\$4) and (die or semiconducotr or chip)) and ((encapsulat\$4 or seal\$4) with (semiconductor or device or die or chip))) and (plural\$6 with (die or semiconducotr or chip or device))) and rib) not (((mold\$4 and ((encapsulat\$4 or seal\$4) with (semiconductor or device or die or chip))) and (plural\$6 with (die or semiconducotr or chip or device))) and rib) and (mold with rib))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/26 16:42
22	5	(US-5914531-\$ or US-6114192-\$).did. or (US-20010032800-\$ or US-20010026665-\$).did. or (FR-2570221-\$).did.	USPAT; US-PGPUB; EPO	2004/06/26 16:49
23	1	(US-5914531-\$).did.	USPAT	2004/06/26 16:52